PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yuan-Chih HSIEH	01/31/2008
Shih-Chang LIU	01/31/2008
Shih-Chi FU	01/30/2008
Tzu-Hsuan HSU	01/31/2008
Chung-yi YU	01/30/2008
Gwo-Yuh SHIAU	01/30/2008
Chia-Shiung TSAI	01/31/2008

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11835814

CH $40.00 11835814

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.924
NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 6 source=24061_924_Assignment#page1.tif source=24061_924_Assignment#page2.tif source=24061_924_Assignment#page3.tif source=24061_924_Assignment#page4.tif source=24061_924_Assignment#page5.tif source=24061_924_Assignment#page6.tif	

Docket No.: 2007-0113 / 24061.924
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1)	Yuan-Chih Hsieh	of	4F, No. 12, Lane 1007, Daxue Road Hsinchu City 300, Taiwan, R.O.C.
(2)	Shih-Chang Liu	of	No. 21-1, Yuku Village, Alian Township Kaohsiung County 822, Taiwan, R.O.C.
(3)	Shih-Chi Fu	of	4F, No. 41, Lane 87, Fuyang Street, Sinyi District Taipei City 110, Taiwan, R.O.C.
(4)	Tzu-Hsuan Hsu	of	No. 72, Gangshan Central Street, Cianjhen District Kaohsiung City 806, Taiwan, R.O.C.
(5)	Chung-Yi Yu	of	14F, No. 18, Alley 6, Lane 485, Sec. 1, Kuang-Fu Rd. Hsin-Chu, Taiwan, R.O.C.
(6)	Gwo-Yuh Shiau	of	No. 6, Lane 267, Shihpin Road Hsinchu City 300
(7)	Chia-Shiung Tsai	of	No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

EMBEDDED BONDING PAD FOR IMAGE SENSORS

for which we have executed an application for Letters Patent of the United States of America,

______ of even date filed herewith; and
X filed on August 8, 2007 and assigned application no. 11/835,814 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., (SMC? , No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yuan-Chih Hsieh

Residence Address: 4F, No. 12, Lane 1007, Daxue Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: 01/31/2008

Inventor Signature

Inventor Name: Shih-Chang Liu

Residence Address: No. 21-1, Yuku Village, Alian Township
Kaohsiung County 822, Taiwan, R.O.C.

Dated: __________

Inventor Signature

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any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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Inventor Name: Yuan-Chih Hsieh

Residence Address: 4F, No. 12, Lane 1007, Daxue Road
Hsinchu City 300, Taiwan, R.O.C.

Dated:____________________ ____________________
Inventor Signature

Inventor Name: Shih-Chang Liu

Residence Address: No. 21-1, Yuku Village, Alian Township
Kaohsiung County 822, Taiwan, R.O.C.

Dated: Shih-Chang Liu 01/31.2008
Inventor Signature

Inventor Name: Shih-Chi Fu

Residence Address: 4F, No. 41, Lane 87, Fuyang Street, Sinyi District
Taipei City 110, , Taiwan, R.O.C.

Dated:____________

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Inventor Signature

Inventor Name: Tzu-Hsuan Hsu

Residence Address: No. 72, Gangshan Central Street, Cianjhen District
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Dated: '08. 1/31

Tzu-Hsuan Hsu
Inventor Signature

Inventor Name: Chung-Yi Yu

Residence Address: 14F, No. 18, Alley 6, Lane 485, Sec. 1, Kuang-Fu Rd.
Hsin-Chu, Taiwan, R.O.C.

Dated:____________

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Inventor Signature

Inventor Name: Gwo-Yuh Shiau

Residence Address: No. 6, Lane 267, Shihpin Road
Hsinchu City 300

Dated:____________

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Inventor Signature

Inventor Name: Shih-Chi Fu

Residence Address: 4F, No. 41, Lane 87, Fuyang Street, Sinyi District
Taipei City 110, , Taiwan, R.O.C.

Dated: 01/30/2008

Shih-Chi Fu
Inventor Signature

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Dated: 01/30/2008

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Inventor Name: Gwo-Yuh Shiau

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Hsinchu City 300

Dated: 01/30/2008

Gwo-Yuh Shiau
Inventor Signature

Inventor Name: Chia-Shiung Tsai

Residence Address: No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road
Kaohsiung City 806, Taiwan, R.O.C.

Dated: 01/31/2008

Chia Shiung Tsai
Inventor Signature
